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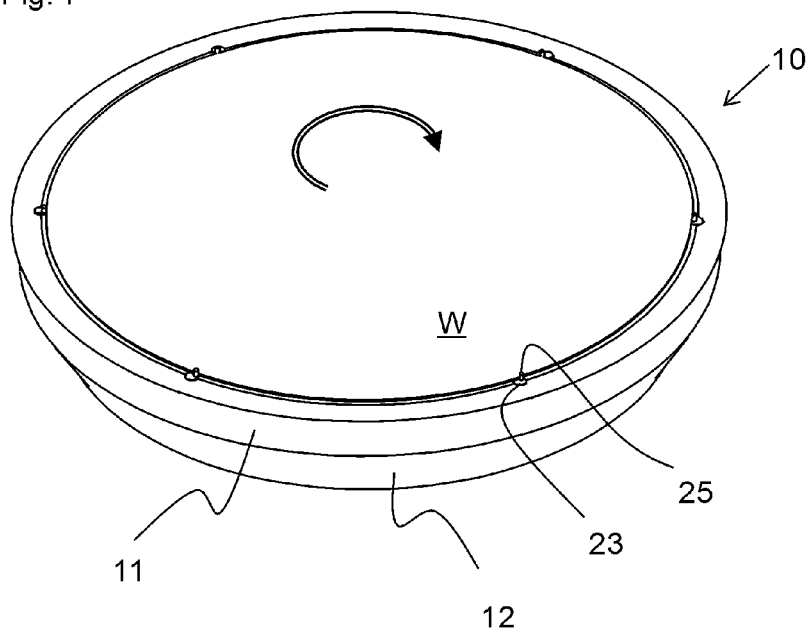
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Declarations under Rule 4.17:

[Continued on next page]

(54) Title: DEVICE FOR HOLDING WAFER SHAPED ARTICLES

Fig. 1



(57) Abstract: A spin chuck for holding semiconductor wafers includes one or more damping mechanisms to limit the force with which chuck pins impact the wafer edge following 5 wafer shift. The damping mechanism may be a linear or rotary dashpot. The dashpot or dashpots are mounted on a surface of the chuck body and include a control arm that contacts a common gear ring that in turn drives the chuck pins during radially inward and outward movement.

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